Statement of Materials, Construction

LEAD-FREE -- 32L QFP -- TABLE OF MATERIAL DECLARATION

No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.02394	Cu	7440-50-8	0.02377	14.11	99.28
				Cr	7440-47-3	0.00005	0.03	0.22
				Sn	7440-31-5	0.00006	0.04	0.25
				Zn	7440-66-6	0.00006	0.04	0.25
2	Die	Silicon Chip	0.00227	Si	7440-21-3	0.00227	1.35	99.99
3	Die Attach Material	Conductive Epoxy	0.00025	Silver (Ag)	7440-22-4	0.00019	0.11	76.00
				Functionalized Urethane	Proprietary	0.00002	0.01	8.00
				Diester Resin	Proprietary	0.00003	0.02	10.50
				Epoxy Resin	Proprietary	0.00001	0.01	5.50
4	Wire	Gold	0.00177	Au	7440-57-5	0.00177	1.05	99.99
5	Lead Finish	Tin	0.00093	Sn	7440-31-5	0.00093	0.55	100
6	Encapsulation	Epoxy Resin	0.13932	Fused Silica	60676-86-0	0.12121	71.94	87.00
				Epoxy Resin	Proprietary	0.01045	6.20	7.50
				Phenol Resin	Proprietary	0.00766	4.55	5.50
Total Package Weight =			0.16849					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%